

## Bluetooth Smart Bond Module

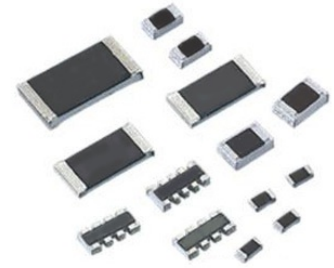
**Manufacturer:** [Renesas Technology Corp](#)

**Package/Case:** SMD

**Product Type:** RF Integrated Circuits

**RoHS:** RoHS Compliant/Lead free 

**Lifecycle:** Active



Images are for reference only

[Inquiry](#)

## General Description

## Key Features

Bluetooth 5.1 core qualified

Integrated antenna

Worldwide certification

Arm<sup>®</sup> Cortex<sup>®</sup>-M0+ at 16MHz

IoTMark<sup>™</sup>-BLE score of 18300

23.75µA/MHz MCU current

Memory: 48kB RAM, 32kB OTP and 1Mb Flash

1.8V to 3.3V supply range

+2.2dBm max output power

-93dBm sensitivity

Rx current 2mA at 3V

Tx current 4mA at 3V at 0dBm

Interfaces: 2xUART, SPI, I<sup>2</sup>C

4-channel 10-bit ADC

8 GPIO

Built-in temperature sensor

Operating temperature: -40 °C to +85 °C

Dimensions: 12.5mm x 14.5mm x 2.8mm

## Recommended For You

---

### DA16200MOD-AAC4WA32

Renesas Technology Corp

QFN

### DA16600MOD-AAE4WA32

Renesas Technology Corp

BGA

### RYZ012A100FZ00#BD0

Renesas Technology Corp

BGA